Shenzhen Leadtek Electronics Co.,Ltd

PRODUCT SPECIFICATION TFT-LCD MODULE

Module No: LTK013QVBLM02-V1

☑ Preliminary Specification

☐ Approval Specification

Designed by	Checked by	Approved by
jona	Tom	lan

Final Approval by Customer

Approved by	Comment
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^{**}The specification of "TBD" should refer to the measured value of sample . If there is difference between the design specification and measured value, we naturally shall negotiate and agree to solution with customer.

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1.Document Revision History

Version	Contents	Date	Note
V0	Original	2022.04.25	
V1	The backlit plastic frame material is changed to black material, and the FPC is brushed with black oil	2022.05.26	
			0 1

2. Introduction

2.1 Scope of application

This specification applies to the LCD module that is supplied by Shenzhen

Leadtek Electronics Co.,Ltd

LCD specification: Dots 240xRGBx240.

As to basic specification of the driver IC, refer to the IC (ST7789V2)

specification and data book.

All material & processing of the LCD module should be Lead Free.

2.2 TFT features:

Structure: TFT PANNEL+IC +FPC+BL;

IPS Type LCD

240dot-segment and 240 dot-common outputs;

262K Color can be selected by software;

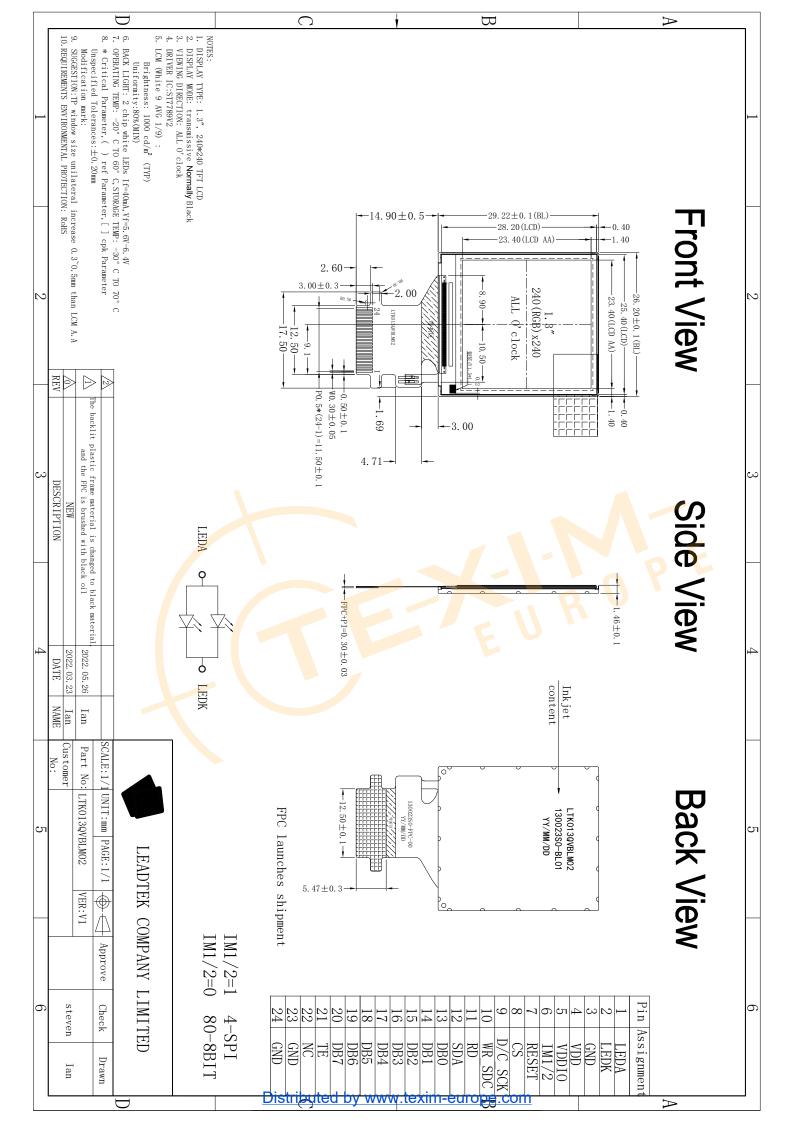
White LED back light;

4line SPI &8bit MCU interface

2.3 Applications:

3. LCM General specification

ITEM	Sandard value	Unit
LCD Type	Normally black	
Drive element	TFT active matrix	
Number of pixels	240(H) RGB × 240(V)	Dots
Pixel arrangement	gement RGB Vertical Stripe	
Pixel Pitch (H*V)	0.0975(H) × 0.0975(V)	mm
Active area	23.40(H) × 23.40(V)	mm
Viewing direction	ALL O'CLOCK	Ĭ
TFT Driver IC	ST7789V2	
TFT interface	4line SPI&8bit MCU interface	-
Approx. Weight	TBD	g
LCM S <mark>iz</mark> e(W*H*T)	26.2 <mark>0(W) ×29.22(H) ×</mark> 1.46(T)	mm



4. Absolute Maximum Rating

Characteristics	Symbol	Min.	Max.	Unit
LCM Operating Temperature	T _{OPR}	-20	+60	°C
LCM Storage Temperature	T _{STG}	-30	+70	°C
Humidity	RH	1	90	%

5.Electrical Characteristics

5.1 TFT DC Characteristics

Characteristics	Symbol	Min.	Тур.	Max.	Unit	Note
Supply Voltage for I/O	VDDIO	1.65	1.8	3.3	V	
Supply Voltage for(DC/DC)	VDD	2.5	2.8	3.3	V	
TFT Gate ON Voltage	VGH	12		18	V	*1,*2
TFT Gate OFF Voltage	VGL	-10		-7	V	*1,*2
TFT Common Voltage	Vcom	-2	1	5	V	*3

Note:

The storage structure of this model is C_{ST}(Storage on Common)

5.2 Back-Light Unit Characeristics

The back-light system is an edge-lighting type with white 2 LEDs. The characteristics of the back-light are shown in the following tables.

Characteristics	Symbol	Min.	Туре	Max.	Unit	Notes
Forward Voltage	V _F	5.6		6.4V		-
Forward current	I _F		40		mA	-
Luminance(With LCD)	Lv		1000		cd/m ²	-
LED life time	N/A		20,000		Hr	Note 1

Note:

(1) The "LED life time" is defined as the module brightness decrease to 50% of original brightness at I_L =20mA/LED. The LED life time could be decreased if operating I_L is larger than 25mA/LED.

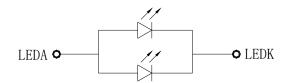
Backlight circuit diagram shown in below:

^{*1.} VGH is TFT Gate operating Voltage.

^{*2.} VGL is TFT Gate operating Voltage.

^{*3.} Vcom must be adjusted to optimize display quality _Cross talk, Contrast Ratio and etc.





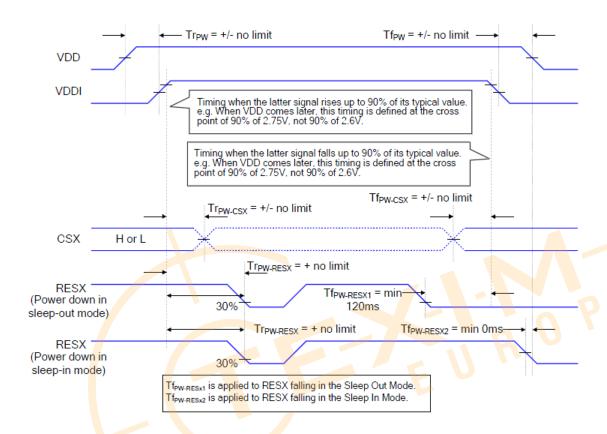
6. Module Function Description

Pin No.	Symbol	LCM Description	remarks
1	LEDA	Power Supply For LED Backlight Anode Input.	
2	LEDK	Power Supply For LED Backlight Anode Input.	
3	GND	Ground	
4	VDD2.8V	Power Supply For LCD. (2.5-3.3V)	
5	VDDIO1.8V	Power Supply For I/O. (1.65-3.3V)	
6	IM1/2	The MCU interface mode select	F
7	RESET	Global reset pin	P
8	CS	Chip select signal input pin	
9	D/C_SCK	Serial clock signal.	
10	WR_SDC	Write strobe signal.	
11	RD	Read strobe signal.	
12	SDA	input/output signal pin	
13~20	DB0~DB7	MCU parallel interface data bus.	
21	TE	Frame head pulse for tearing effect.	
22	NC	NC	
23~24	GND	Ground	

7. Timing Characteristics

Power ON/OFF Sequence

The power on/off sequence is illustrated below



8080 Series MCU Parallel Interface Characteristics: 18/16/9/8-bit Bus:

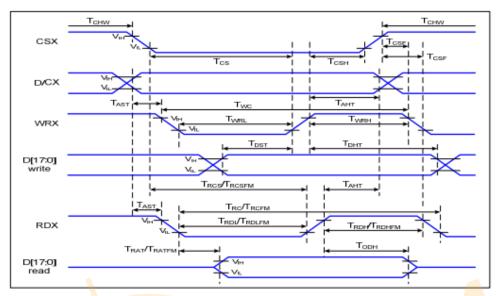


Figure 1 Parallel Interface Timing Characteristics (8080-Series MCU Interface)

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	Min	Max	Unit	Description
D/CX	Tast	Address setup time	0		ns	
DICX	T _{AHT}	Address hold time (Write/Read)	10		ns	Q U
	T _{CHW}	Chip select "H" pulse width	0		ns	
	Tcs	Chip select setup time (Write)	15	E	ns	
004	Trcs	Chip select setup time (Read ID)	45		ns	
CSX	TROSEM	Chip select setup time (Read FM)	355		ns	-
	T _{CSF}	Chip select wait time (Write/Read)	10		ns	
	Тсзн	Chip select hold time	10		ns	
	Twc	Write cycle	66		ns	
WRX	TWRH	Control pulse "H" duration	15		ns	
	T _{WRL}	Control pulse "L" duration	15		ns	
	T _{RC}	Read cycle (ID)	160		ns	
RDX (ID)	T _{RDH}	Control pulse "H" duration (ID)	90		ns	When read ID data
	TRDL	Control pulse "L" duration (ID)	45		ns	
DDV	T _{RCFM}	Read cycle (FM)	450		ns	Milhon mod from
RDX	T _{RDHFM}	Control pulse "H" duration (FM)	90		ns	When read from
(FM)	T _{RDLPM}	Control pulse "L" duration (FM)	355		ns	frame memory
D[17:0]	Tost	Data setup time	10		ns	For CL=30pF



8080 Serial Interface Characteristics (4-line serial):

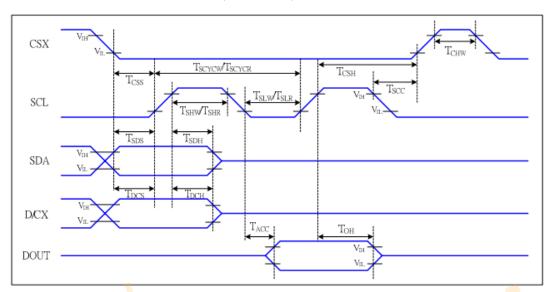


Figure 5 4-line serial Interface Timing Characteristics

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25℃

Signal	Symbol	Parameter	MIN	MAX	Unit	Description	
	Tcss	Chip select setup time (write)	15	7	ns	D	
	T _{CSH}	Chip select hold time (write)	15		ns		
CSX	T _{CSS}	Chip select setup time (read)	60		ns	H	
	Tscc	Chip select hold time (read)	65	C	ns		
	T _{CHW}	Chip se <mark>lect</mark> "H" pulse width	40		ns		
	Tscycw	Serial clock cycle (Write)	66		ns		
	T _{SHW}	SCL "H" pulse width (Write)	15		ns	-write command & data ram	
SCL	Tstw	SCL "L" pulse width (Write)	15		ns		
SOL	Tscycr	Serial clock cycle (Read)	150		ns	-read command & data	
	T _{SHR}	SCL "H" pulse width (Read)	60		ns		
	TslR	SCL "L" pulse width (Read)	60		ns	ram	
D/CX	T _{DCS}	D/CX setup time	10		ns		
DICX	T _{DCH}	D/CX hold time	10		ns		
SDA	Tsps	Data setup time	10		ns		
(DIN)	TsdH	Data hold time	10		ns		
DOUT	T _{ACC}	Access time	10	50	ns	For maximum CL=30pF	
5001	Тон	Output disable time	15	50	ns	For minimum CL=8pF	

Table 6 4-line serial Interface Characteristics

Note: The rising time and falling time (Tr, Tf) of input signal are specified at 15 ns or less. Logic high and low levels are specified as 30% and 70% of VDDI for Input signals.



Reset Timing:

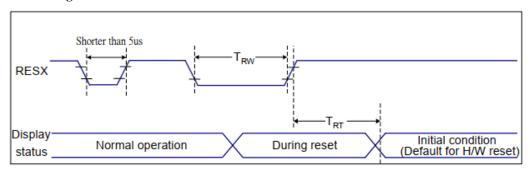


Figure 7 Reset Timing

VDDI=1.65 to 3.3V, VDD=2.4 to 3.3V, AGND=DGND=0V, Ta=25 ℃

Related Pins	Symbol	Parameter	MIN	MAX	Unit
	TRW	Reset pulse duration	10	-	us
RESX	TOT	Reset cancel	-	5 (Note 1, 5)	ms
	TRT			120 (Note 1, 6, 7)	ms

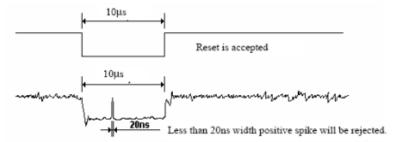
Table 9 Reset Timing

Notes:

- 1. The reset cancel includes also required time for loading ID bytes, VCOM setting and other settings from NVM (or similar device) to registers. This loading is done every time when there is HW reset cancel time (tRT) within 5 ms after a rising edge of RESX.
 - 2. Spike due to an electrostatic discharge on RESX line does not cause irregular system reset according to the table below:

RESX Pulse	Action
Shorter than 5us	Reset Rejected
Longer than 9us	Reset
Between 5us and 9us	Reset starts

- 3. During the Resetting period, the display will be blanked (The display is entering blanking sequence, which maximum time is 120 ms, when Reset Starts in Sleep Out –mode. The display remains the blank state in Sleep In –mode.) and then return to Default condition for Hardware Reset.
 - 4. Spike Rejection also applies during a valid reset pulse as shown below:



- 5. When Reset applied during Sleep In Mode.
- 6. When Reset applied during Sleep Out Mode.
- It is necessary to wait 5msec after releasing RESX before sending commands. Also Sleep Out command cannot be sent for 120msec.



8. Optical Characteristics

Parameter			Symbol	Condition	Min.	Тур.	Max.	Unit	Remark
Threshold Voltage		Vsat		4.1	4.3	4.5	V	Fig.1	
		Vth		1.6	1.8	2.0	V		
Viewing Angle	Horizontal		Θ3	CR>10	70	80		0	Note 1
			Θ9		70	80		0	
	Vertical		Θ12		70	80		0	
	veru	ICal	Θ6		70	80		0	
Contrast Ratio		CR	Θ= 0°	600	800			Note 2	
Transmittance		T(%)	Θ= 0°	4.1	4.59			Note 3	
NTSC		%	Θ= 0°	45	50				
Reproduction Of color	Red	Rx		0.610	0.625	0.640		Note 4	
		Ry		0.295	0.310	0.325			
	n [Croon	Gx	Θ= 0°	0.280	0.295	0.310		filter Glass with OC
		Green	Gy		0.503	0.518	0.533		
	Blue	Pluo	Bx		0.127	0.142	0.157		
		blue	Ву		0.128	0.143	0.158		
White		Wx	Θ= 0°		TBD				
		Wy			TBD				
Response Time		Tr+Tf	Θ= 0°		30	35	ms	Note 5	

Note:

- 1. Viewing angle is the angle at which the contrast ratio is greater than 10. The viewing are determined for the horizontal or 3, 9 o'clock direction and the vertical or 6, 12 o'clock direction with respect to the optical axis which is normal to the LCD surface (see FIG.2).
- 2. Contrast measurements shall be made at viewing angle of Θ = 0° and at the center of the LCD surface. Luminance shall be measured with all pixels in the view field set first to white, then to the dark (black) state. (See FIG. 2) Luminance Contrast Ratio (CR) is defined mathematically.

- Transmittance is the value without APF Pol.
- 4. The color chromaticity coordinates specified in Table1 shall be calculated from The spectral data measured with all pixels first in red, green, blue and white. Measurements shall be made at the center of the C/F. Measurement condition is C light source & Halogen Lamp
- The electro-optical response time measurements shall be made as FIG.3 by switching the "data" input signal ON and OFF.

The times needed for the luminance to change from 10% to 90% is Tr, and 90% to 10% is Tf.



Figure 1. The definition of Vth & Vsat

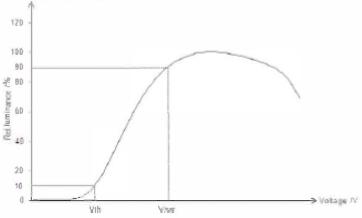


Figure 2. Measurement Set Up

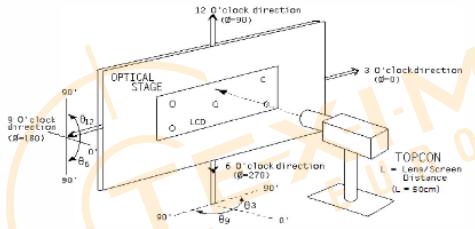
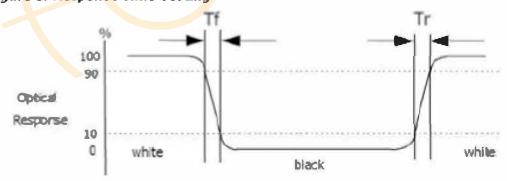


Figure 3. Response Time Testing



9. Reliability Test Item

No.	Test Item	Test Condition	Notes			
1	High Temp. Storage	+70°C / 96H	1. Functional test isOK.			
2	Low Temp. Storage	-30°C / 96H	Missing Segment, short, unclear segment non-display, display abnormally			
3	High Tempe. Operating	+60°C / 96H				
4	Low Tempe. Operating	-20°C / 96H	and liquid crystal leakare			
5	High Temperature /Humidity storage	50°C x 90%RH / 96H	un-allowed. 2. No low			
6	Thermal and cold shock	Static state, -30°C (30min) ~60°C (30min), 50 cycles	temperature bubbles,end seal loose andfall, frame rainbow.			

10. Packing Method-----TBD

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Texim Europe - contact details



Headquarters & Warehouse

Elektrostraat 17 NL-7483 PG Haaksbergen The Netherlands

T: +31 (0)53 573 33 33 E: info@texim-europe.com Homepage: www.texim-europe.com









The Netherlands

Elektrostraat 17 NL-7483 PG Haaksbergen

T: +31 (0)53 573 33 33 E: nl@texim-europe.com



Belgium

Zuiderlaan 14, box 10 B-1731 Zellik

T: +32 (0)2 462 01 00 E: belgium@texim-europe.com



UK & Ireland

St Mary's House, Church Lane Carlton Le Moorland Lincoln LN5 9HS

T: +44 (0)1522 789 555 E: uk@texim-europe.com



Germany - North

Bahnhofstrasse 92 D-25451 Quickborn

T: +49 (0)4106 627 07-0 E: germany@texim-europe.com



Germany - South

Martin-Kollar-Strasse 9 D-81829 München

T: +49 (0)89 436 086-0 E: muenchen@texim-europe.com



Austria

Warwitzstrasse 9 A-5020 Salzburg

T: +43 (0)662 216 026 E: austria@texim-europe.com



Nordic

Stockholmsgade 45 2100 Copenhagen

T: +45 88 20 26 30 E: nordic@texim-europe.com



Italy

Via Matteotti 43 IT-20864 Agrate Brianza (MB)

T: +39 (0)39 9713293 E: italy@texim-europe.com